ABBOGIATION CONNECTING ELECTRONICS INDUSTRIES OF INTERNATION CONNECTING	IPC. Bannockl	ourn. Illinois. A	ll rights reserved u ntions.	nder both	This docume level parts, t	ent is a declaratio he declaration en	n of the substand compasses all lo	es within the manufactur wer level materials for w	rer listed ite hich the m	em. Note: if anufacturer	the item is an as has engineering	sembly with lower responsibility.	
				Form Type Distribute									
Supplier Information													
Company name* Company			iy unique ID			Unique ID Authority				Response Date*			
onsemi										2025-05-18			
Contact Name Title - Contac			tact			Phone - Contact*			Email - Contact*				
Product-Env-Stewards Product Envi			viro Compliance		NA			Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Representative			esentative			Phone - Representative*			Email - Representative*				
Product-Env-Stewards Product Env			nviro Compliance		NA			Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		Veight*	UOM	Unit Type	
	ES2B	ES2B UFR S		UFR SMB PN 2A 100V		2025-05-18		TSCBE		2.0	mg	Each	
Manufacturing Proccess Informa	ntion							-					
Terminal Plating / Grid Array M	Terminal Plating / Grid Array Material Terminal Base A		Alloy J	J-STD-020 MSL Rating			Peak Process Body Temperature Max Time at Peak Te			Temperature Number of Reflow Cycles			
Matte Tin (Sn) - annealed CU Alloy		1	1		260	С	30	second	ls 3				
Comments													
evel 1 - maximum time at peak temperat	ure during so	ldering is 10-3	0 seconds										
or more information regarding materia	l composition	please refer to	page 3										

RoHS Material Composition Declar	ation			Declaration Type *	Detailed
Directive 2015/863/EU amending Rol Directive 2011/65/EU	(Pb), Mercury (Hg), Hexav		ninated Biphenyls (PBB), Polybror	dmium and quantity limit of 0.1% by mass (100 ninated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polyb contains a RoHS restricted substance i encompass all such components.Suppl as of the date that Supplier completes Company acknowledges that Supplier independently verified information pro- certification in this paragraph.If the Co	rominated biphenyls and/or polybror nexcess of an applicable quantity lim ier certifies that it gathered the inforr this form.Supplier acknowledges that may have relied on informationprovi ovided by others, Supplier agrees that ompany and the Supplier enter into a clusivesource of the Supplier's liabili	ninated diphenyl ethers (each a "R it, please indicate below which, if nation it provides in this form usin Company will rely on this certifud ded by others in completing this f , at a minimum, itssuppliers have written agreement with respect to ty and the Company's remedies for	toHS restricted substance") in exce any, RoHS exemption you believe ag appropriate methods to ensure it cation in determining the complian orm, and that Supplier may not hav provided certifications regarding th the identified part, the terms and co or issues that arise regarding inform	ropean Union member states) of the part identifies so of the applicable quantity limit identified about may apply. If the part is an assembly with lows a accuracy and that such information is true and ce of its products with European Union member re independently verified such information. How heir contributions to the part, and those certifica motions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of
<b>RoHS Declaration *</b> 4	- Item(s) does not contain RoHS restr	icted substances per the definition	above except for selected exempti	ons Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high meltin Exemption: 7c-I Electrical and elect	g temperature type solders (i.e. lead ronic components containing lead i	l based solder alloys containing n a glass or ceramic other than	85% by weight or more lead). dielectric ceramic in capacitors, o	e.g. piezoelectronic devices, or in a glass or ce	eramic matrix compound.
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the rec Requester) and click on Submit For			Supplier Acceptance drop-down	. This will display the signature area. Digital	ly sign the declaration (if required by the
Supplier Digital Signature	Rastislav Drska	Le			

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.764	mg	Supplier	Silicon (Si)	7440-21-3		0.6876	mg
			В	Nickel (Ni)	7440-02-0		0.005	mg
			Supplier	Gold (Au)	7440-57-5		0.0011	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.0703	mg
Die Attach Solder	2.25	mg	Supplier	Silver (Ag)	7440-22-4		0.0563	mg
			А	Lead (Pb)	7439-92-1	7a	2.0812	mg
			Supplier	Tin (Sn)	7440-31-5		0.1125	mg
Lead Frame	34.0437	mg	Supplier	Iron (Fe)	7439-89-6		0.0409	mg
			Supplier	Copper (Cu)	7440-50-8		33.9926	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0102	mg
Mold Compound-Black	54.234	mg		Metal Hydroxide	proprietary data		1.8982	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		4.3387	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2712	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		43.3872	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		4.3387	mg
Plating	0.7083	mg	Supplier	Tin (Sn)	7440-31-5		0.7083	mg